

P2002, 0076

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Barbara Vasquez et al.
Applic. No. : 10/062,942
Filed : January 31, 2002
Title : Method of Applying a Bottom Surface
Protective Coating to a Wafer, and Wafer
Dicing Method
Examiner : Angel Roman Group Art Unit: 2812

D E C L A R A T I O N under 37 C.F.R. § 1.131

The undersigned Barbara Vasquez, David Wallis, and Sylvia Winter (hereinafter referred to as "Inventors") hereby declare:

The claimed invention of the above-identified application was "reduced to practice" at least as early as one day prior to August 30, 2001, and/or was conceived coupled with due diligence from prior to August 30, 2001 to the filing date of the above-identified application.

The undersigned Inventors personally wrote an Invention Disclosure form and/or supervised the writing of the patent application during the time from June 6, 2001, when the Invention Disclosure was first received in the Siemens Patent Department, to January 31, 2002 when the above-identified

-1-

patent application was filed at the United States Patent Office.

Enclosed, as corroborating evidence, is the Invention Disclosure SC300 signed by all of the Inventors as of May 22, 2001, which substantiates that the undersigned Inventors invented and "reduced to practice" or conceived the claimed invention of the instant patent application at least as early as one day prior to August 30, 2001.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Barbara Vasquez

Date: _____, 2003



David Wallis

Date: 26 FEBRUARY, 2003

Sylvia Winter

Date: _____, 2003

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Barbara Vasquez
Barbara Vasquez

Date: Jan 31, 2003

David Wallis
David Wallis

Date: _____, 2003

Sylvia Winter
Sylvia Winter

Date: _____, 2003

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Barbara Vasquez

Date: _____, 2003

David Wallis

Date: _____, 2003

Sylvia Winter
Sylvia Winter

Date: January 29th, 2003

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